	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	355	(438/111).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:04
2	BRS	L10	0	((seal$4 near2 resin) near8 (cavit$4) near8 mold$4) with (spacer$3) with (groov$4 or gap$4 or via or vias or hole or holes or channel$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
3	BRS	L12	156	((seal$4 near2 resin) near8 (cavit$4) near8 mold$4) same (groov$4 or gap$4 or via or vias or hole or holes or channel$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
4	BRS	L15	1124	(lead near2 frame) with (seal$4 or clos$4 or encapsulat$4 or fasten$4) with (resin or epoxy) with (cavit$3 or via$3 or hole$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
5	BRS	L16	55346	"lead frame"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L17	641	(seal$4 near2 resin) near8 (cavit$4) near8 mold$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
7	IS&R	L19	1060	(438/123).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
8	IS&R	L20	3587	(257/666).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
9	BRS	L21	4644	((438/111).CCLS.) or ((438/123).CCLS.) or ((257/666).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
10	IS&R	L23	355	(438/111).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L2	534	(lead near2 frame) near8 (seal$4 or clos$4 or encapsulat$4 or fasten$4) near8 (resin or epoxy) near8 (cavit$3 or via$3 or hole$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
12	BRS	L3	6	((lead near2 frame) near8 (seal$4 or clos$4 or encapsulat$4 or fasten$4) near8 (resin or epoxy) near8 (cavit$3 or via$3 or hole$3)) and ((438/111).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
13	BRS	L4	20	((lead near2 frame) near8 (seal$4 or clos$4 or encapsulat$4 or fasten$4) near8 (resin or epoxy) near8 (cavit$3 or via$3 or hole$3)) and ((438/123).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
14	IS&R	L5	1060	(438/123).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:05
15	IS&R	L6	3587	(257/666).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:06

	Type	L #	Hits	Search Text	DBs	Time Stamp
16	BRS	L7	40	((lead near2 frame) near8 (seal$4 or clos$4 or encapsulat$4 or fasten$4) near8 (resin or epoxy) near8 (cavit$3 or via$3 or hole$3)) and ((257/666).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:06
17	BRS	L8	2	(lead adj frame) same (seal$4 near2 resin) same (outer adj lead) same (inner adj lead) same (hard$8 near4 resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:06
18	BRS	L9	162	((seal$4 near2 resin) near8 (cavit$4) near8 mold$4) same "lead frame"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:06
19	BRS	L11	1	((seal$4 near2 resin) near8 (cavit$4) near8 mold$4) same (spacer$3) same (groov$4 or gap$4 or via or vias or hole or holes or channel$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:06
20	BRS	L13	113	(((seal$4 near2 resin) near8 (cavit$4) near8 mold$4) same (groov$4 or gap$4 or via or vias or hole or holes or channel$3)) not (((seal$4 near2 resin) near8 (cavit$4) near8 mold$4) same "lead frame")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:07
21	IS&R	L14	1	("6,603,194").PN.	USPAT	2004/08/31 10:06

	Type	L #	Hits	Search Text	DBs	Time Stamp
22	BRS	L18	162	((seal$4 near2 resin) near8 (cavit$4) near8 mold$4) same "lead frame"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:06
23	BRS	L22	47	((seal$4 near2 resin) near8 (cavit$4) near8 mold$4) and (((438/111).CCLS.) or ((438/123).CCLS.) or ((257/666).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:06
24	BRS	L24	58371	leadframe or "lead frame"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:07
25	BRS	L25	8988	outer adj lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:07
26	BRS	L26	2467343	resin or sealing or (fill$6 adj material)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:08

	Type	L #	Hits	Search Text	DBs	Time Stamp
27	BRS	L27	631226	removable or detachable or cutaway	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:08
28	BRS	L28	731337	mold or molding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:09
29	BRS	L29	65	24 and 25 and 26 and 27 and 28	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:23
30	IS&R	L32	336	(438/110).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:24
31	IS&R	L33	355	(438/111).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:24

	Type	L #	Hits	Search Text	DBs	Time Stamp
32	IS&R	L34	461	(438/112).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:24
33	IS&R	L35	770	(438/113).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:24
34	IS&R	L36	1060	(438/123).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:25
35	IS&R	L37	552	(438/666).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:25
36	BRS	L38	2975	32 or 33 or 34 or 35 or 36 or 37	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:25

	Type	L #	Hits	Search Text	DBs	Time Stamp
37	BRS	L39	188	38 and 24 and 25 and 28	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:26
38	BRS	L40	135	39 and (@ad<20010920)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 10:26

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L28	2065	(257/678).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 16:38
2	BRS	L29	58734	"lead frame"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 16:38
3	BRS	L30	1040618	portable or detachable or removable or jig	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 16:39
4	BRS	L31	209	26 and 29 and 30	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 17:01
5	BRS	L36	15	27 and 29 and 30	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 17:20

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L37	64	28 and 29 and 30	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 18:52
7	IS&R	L38	3587	(257/666).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 18:27
8	IS&R	L27	331	(257/674).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 18:37
9	BRS	L39	277	leadframe and (resin or epoxy or encapsulant) and (removable or portable or detachable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:11
10	IS&R	L40	355	(438/111).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:12

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	IS&R	L45	1060	(438/123).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:29
12	IS&R	L46	336	(438/110).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:49
13	BRS	L48	189	39 and (@ad<20010920)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:03
14	IS&R	L49	603	(438/121).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:03
15	IS&R	L50	461	(438/112).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:16

	Type	L #	Hits	Search Text	DBs	Time Stamp
16	IS&R	L51	770	(438/113).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:35